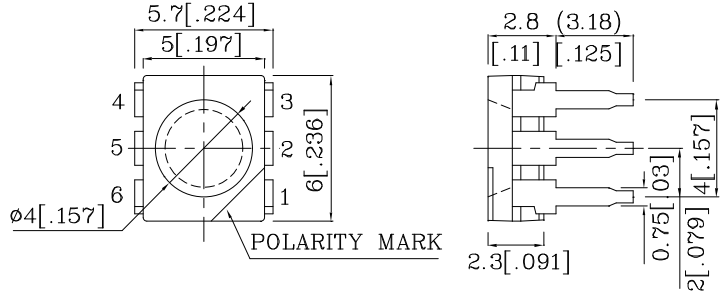


PRELIMINARY SPEC

Features

- OUTSTANDING MATERIAL EFFICIENCY.
- RELIABLE AND RUGGED.
- WATER CLEAR LENS.
- LOW POWER CONSUMPTION.
- ONE BLUE, ONE RED AND ONE GREEN CHIPS IN ONE PACKAGE.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE

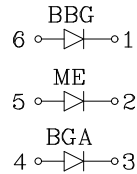


Notes:

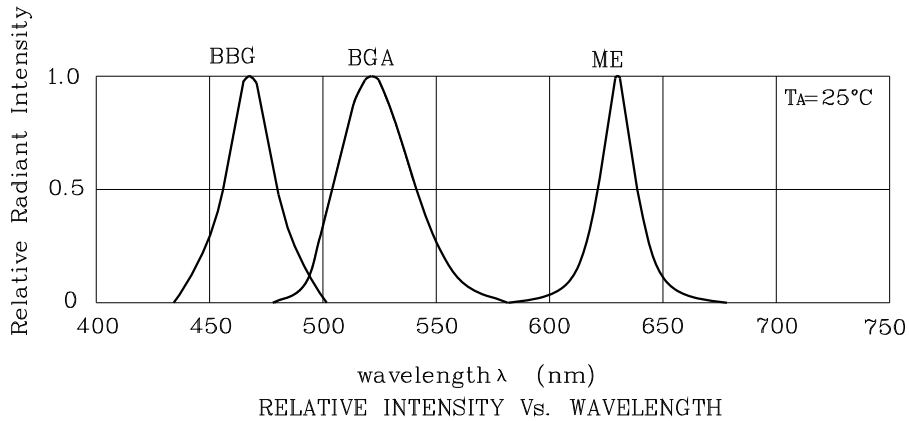
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		BBG (InGaN)	ME (InGaAlP)	BGA (InGaN)	Unit
Reverse Voltage	VR	5	5	5	V
Forward Current	IF	30	50	30	mA
Forward Current (peak) 1/10Duty Cycle 0.1ms Pulse Width	iFS	100	195	100	mA
Total Power Dissipation Within 350mW At All Chips Are Lightened	PT	350			mW
Electrostatic Discharge Threshold (HBM)		1000	-	1000	V
Operating Temperature	TA	-40 ~ +85			°C
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]		260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]		260°C For 5 Seconds			

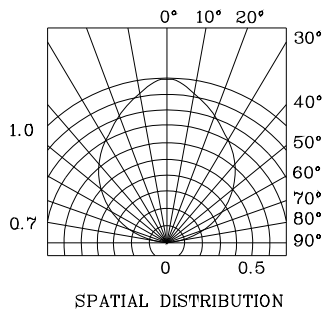
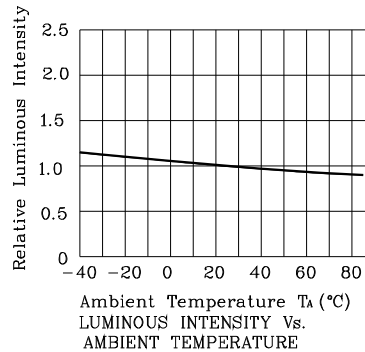
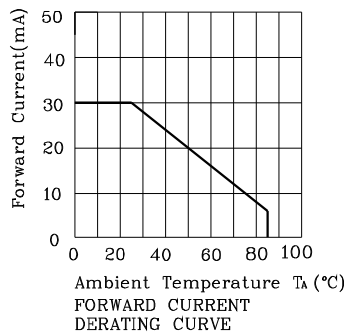
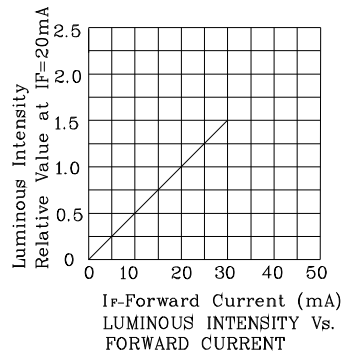
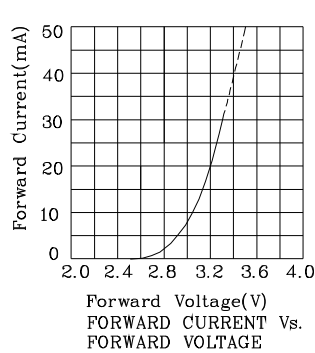
Operating Characteristics (TA=25°C)		BBG (InGaN)	ME (InGaAlP)	BGA (InGaN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	3.2	2.0	3.2	V
Forward Voltage (Max.) (IF=20mA)	VF	4.0	2.5	4.0	V
Reverse Current (Max.) (VR=5V)	IR	10	10	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λP	468	630	520	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λD	470	621	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	21	20	35	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	100	25	100	pF



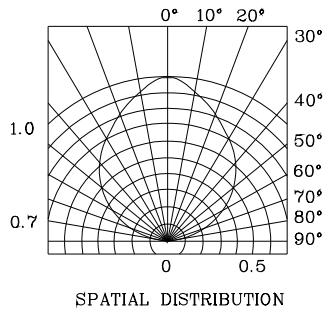
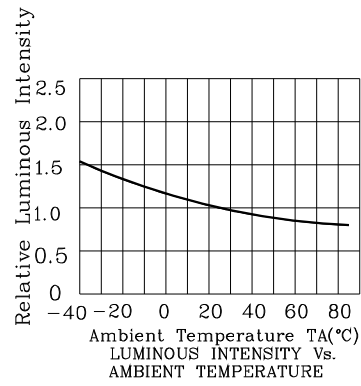
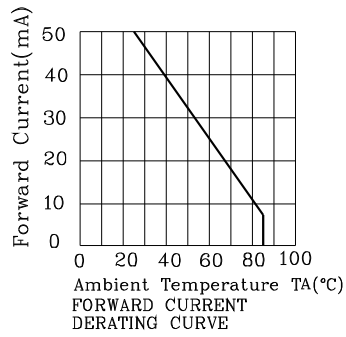
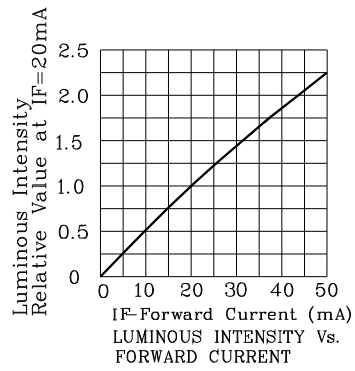
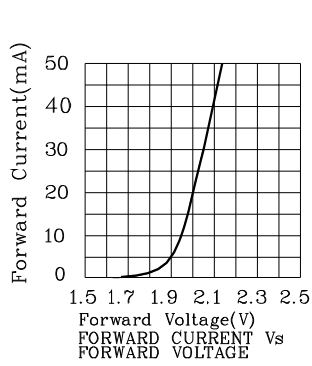
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=30mA *50mA) mcd		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
XSBBGMEBGA99W	Blue	InGaN	Water Clear	180	297	468	100°
	Red	InGaAlP		*650	*995	640	
	Green	InGaN		180	347	520	



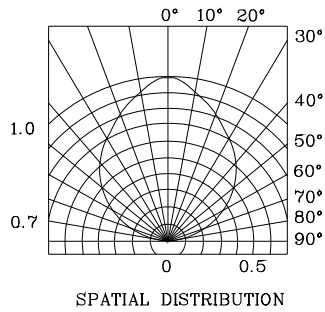
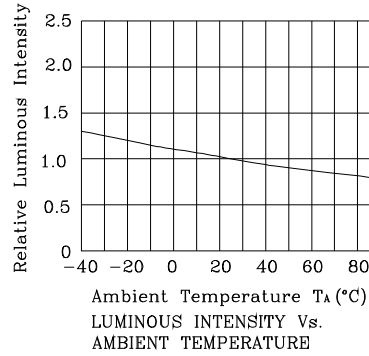
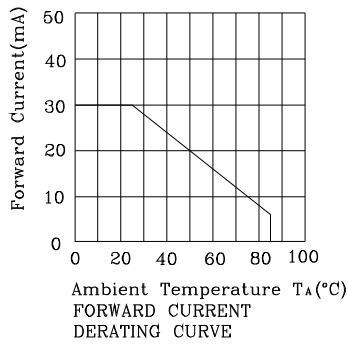
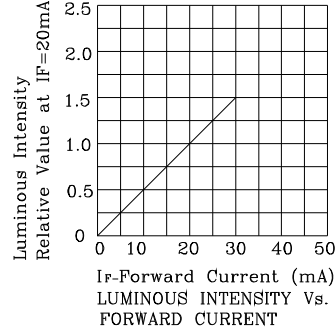
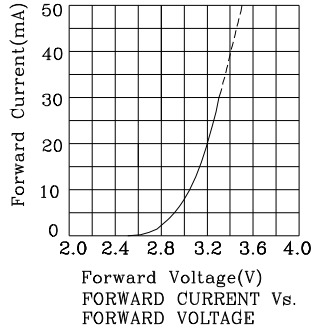
❖ **BBG**



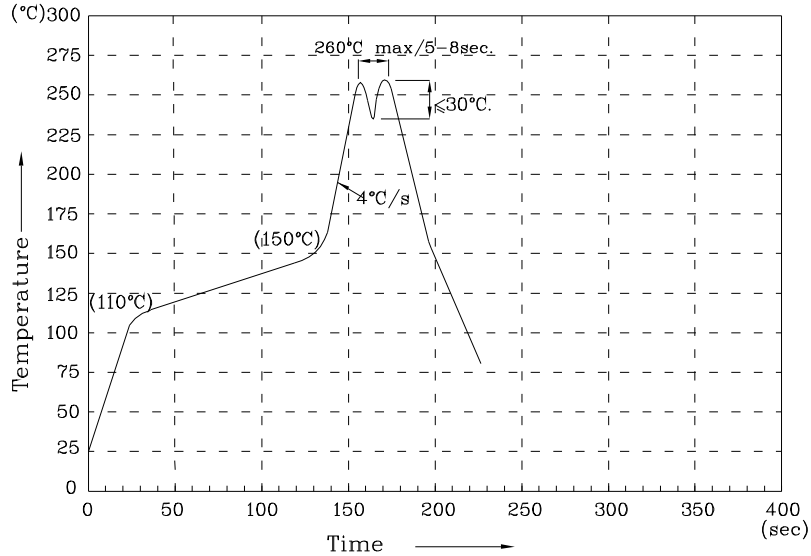
❖ ME



❖ BGA



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

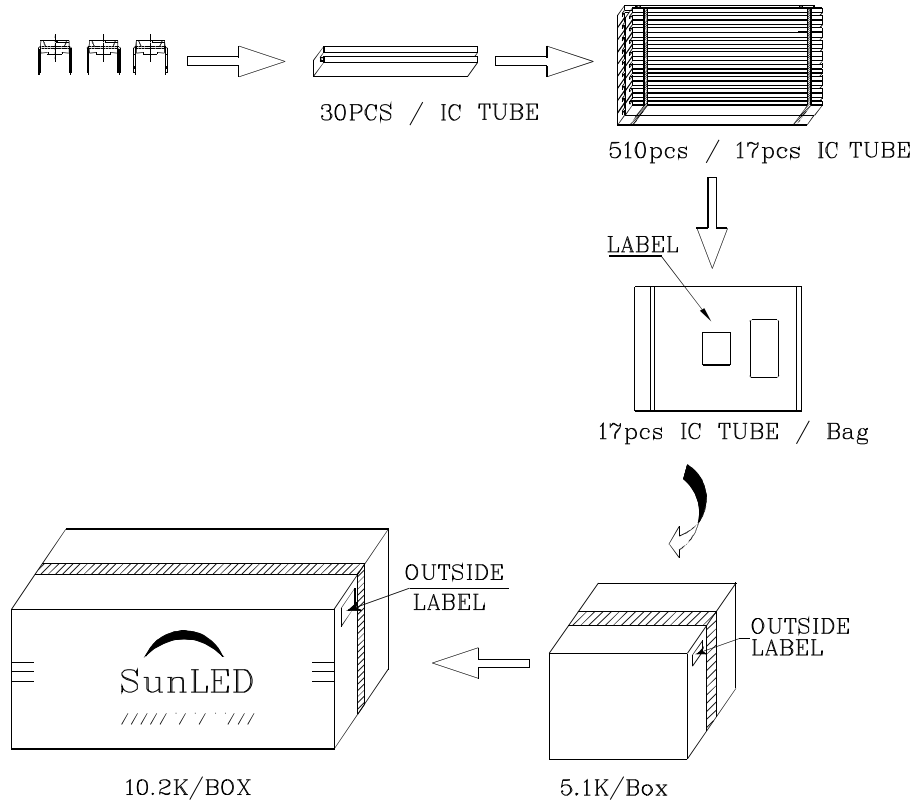

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

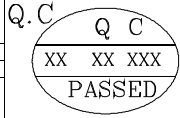

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS

XSBBGMEBGA99W

	
P/NO : XSxxx99x	
QTY : 30 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	